

Multi-Gigabit Interfaces for Communications/Datacomm

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Outline

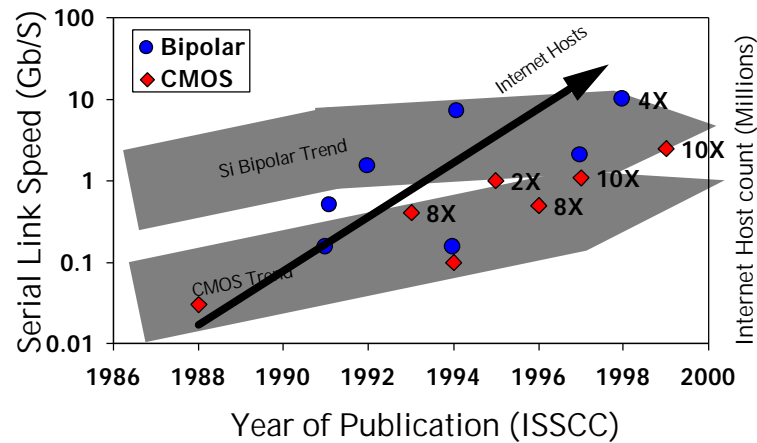
- Silicon trends
- 10Gb/s options
- Physical component infrastructure
- Coding
- Jitter
- Conclusions



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Silicon trends in data links



After R. Walker "Clock and Data Recovery for Serial Digital Comm", BCTM98



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General silicon trend

- Current Bipolar technology can handle data rates in excess of 10Gb/s
 - Oversampling can push this even higher
 - Rates will continue to increase with SiGe process development
 - Electronics is challenging, but not the gating item at 10Gb/s
- CMOS is progressing at approximately Moore's Law pace
 - High interleaving rates may adversely effect jitter performance
- Electronics are not keeping pace with bandwidth demand
 - Aggregation of multiple serial channels are going to be necessary for backplanes, servers, etc



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10 x ~1Gb/s channel aggregate link

- 10 channels at ~1Gb/s/channel
 - Technology and specs (1000BASE-X) available today for electronics
 - May allow CMOS implementation
 - Can be used over backplane using FR4 and standard connectors
 - Parallel fiber offers long distance extension



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4 x ~2.5Gb/s aggregate link

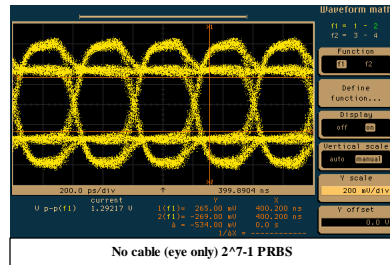
- 2.5 Gb/s links available today
 - Bipolar and GaAs in production
 - May be within CMOS reach in future
- Backplanes with FR4 and low cost connectors may be implemented at these rates
- Copper cable distances of >15 meters are reasonable
- Multiple market segments at this rate will accelerate development and lower cost
 - Backplanes, OC48, Fiber Channel, Server links



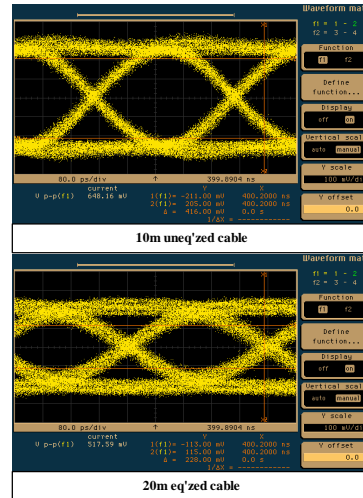
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Copper cable operating at 2.5 GbD Si Bipolar process (HP25)



- Signals are PRBS ($2^7 - 1$) from 2.5 GbD SerDes which includes pre-emphasis output.
- Two different lengths of BERG MetaGig™ cable
10m (unequalized cable) and 20m (equalized cable)
- MetaGig is shielded quad cable with HSSDC-style connectorization.



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1x ~10Gb/s serial link

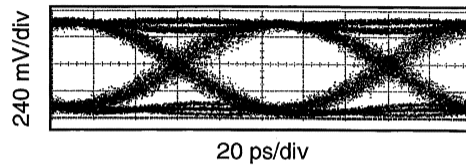
- Electronics may not be gating item at 10Gb/s
 - SONET OC192 links working today
 - SiGe will extend range of Bipolar links
 - BUT media capability will be challenged
 - Low cost optics available?
 - Copper cables, PCB performance limitations will constrain applications and reduce volume
 - Jitter performance in optical links?



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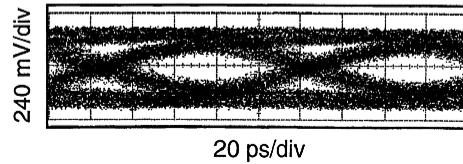
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10 Gb/s SERDES performance Si Bipolar process (HP25) Eye Diagrams



Eye at package Pin

- 3ps (RMS) / 18ps (p-p)
- systematic jitter < 3ps (peak)



*Eye after 21' of
0.19" coax*

- BER < 10^{-14}

After R. Walker et al, "A 10Gb/s Si-Bipolar TX/RX chipset for Computer Data Transmission", ISSCC 98



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Physical component infrastructure

- PBC, connectors, and cables need to be examined closely at these higher rates
- Jitter budgets will be affected by PCB lengths, connectors, etc
- Distance requirements need to be defined
 - PCB to PCB distance for backplane
 - PCB to cable connector distance
 - Minimum required cable length = ?? m
- Implications at 2.5 Gb/s vs. 10 Gb/s

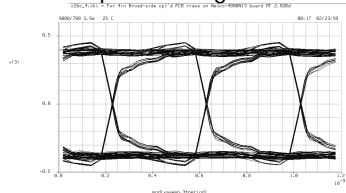


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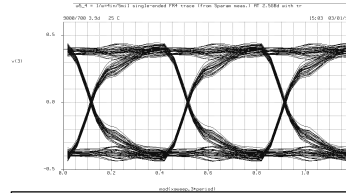
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2.5 GBd PCB performance

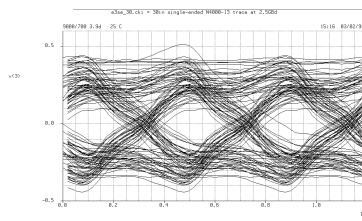
- Both FR4 and N4000-13 show > 24 inch performance with unequalized signals



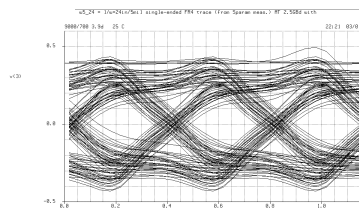
N4000-13: 4in (5mil) trace at 2.5 GBd



FR4: 4in (5mil wide) trace at 2.5 GBd



N4000-13: 30in with input=2.5GBd



FR4: 24in, 2.5GBd, input tr=50ps

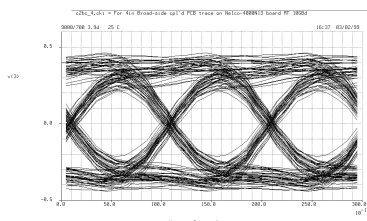


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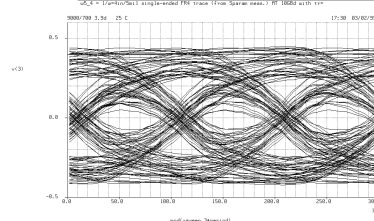
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10 GBd PCB performance

- FR4 limited to ~4 inches (unequalized signals)
- N4000-13 significantly improves performance
 - Tx pre-emphasis could improve eye margin



N4000-13: 4in (5mil wide) trace at 10 GBd



FR4: 4in (5mil) trace at 10 GBd



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Coding options

- 8b/10b code requires 25% bandwidth overhead
 - 2.5Gb/s --> 3.125Gbd
 - 10Gb/s --> 12.5Gbd
 - Silicon can accommodate rate increase
 - PCB, connector performance will degrade slightly
- 16b/18b codes, others?
 - May affect jitter budgets due to run lengths, balance specifics, etc.
 - Any candidate code needs to be examined ASAP

Scaled optical jitter budget requirements

- SERDES scaled transmitter requirements (@ TP1):
 - 2.5 Gbd extrapolation: RJ = 56ps, DJ = 40ps, **TJ = 96ps**
 - 10 Gbd extrapolation: RJ = 14ps, DJ = 10ps, **TJ = 24ps**
- Typical measured data:
 - 2.5Gbd: RJ ~ 84ps, DJ ~ 20ps, **Total ~ 104ps**
 - including PCB trace
 - 10Gbd: RJ ~ 42ps, DJ ~ 10ps, **Total = 52ps**

Jitter requirements

- All elements of a design need to be considered in link budget
 - PCB material, connector loss greatly increased
- 2.5 Gb/s designs appear to have adequate jitter performance
 - link budget modifications possible?
 - SERDES may be built into optical module?
- 10 Gb/s Si Bipolar SERDES designs will not meet current scaled optical link budget restrictions without modifications
 - Retiming must be done inside optical module
 - SiGe may be needed if optical jitter budget cannot be modified
 - Jitter budget too restrictive?



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Conclusion

- 10x 1.0 Gb/s aggregate channel is quickest, lowest cost silicon solution
 - Requires parallel fiber for longer distance
- 4x 2.5 Gb/s aggregate channel is reasonable today for backplane, cable, or optical applications
- 10Gb/s serial electrical performance has been shown for >1 year, but may have application issues
 - Not suitable for backplanes with FR4
 - Short cable lengths possible (1 m - 10m range)
 - Optical jitter budget may demand SiGe, as well as packaging improvements



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